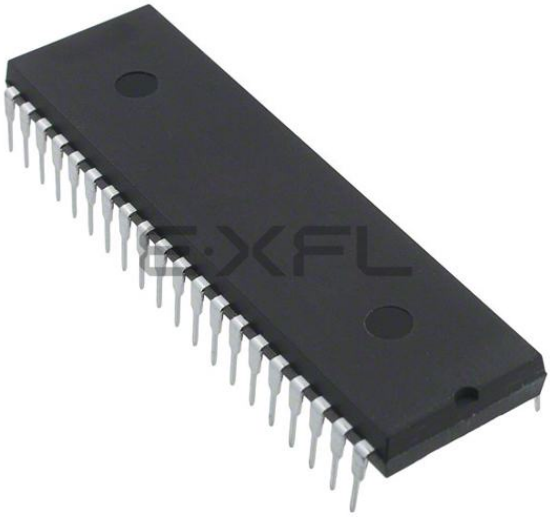

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f45k22-i-p

1.0 DEVICE OVERVIEW

This document contains device specific information for the following devices:

- PIC18F23K22
- PIC18F24K22
- PIC18F25K22
- PIC18F26K22
- PIC18F43K22
- PIC18F44K22
- PIC18F45K22
- PIC18F46K22
- PIC18LF23K22
- PIC18LF24K22
- PIC18LF25K22
- PIC18LF26K22
- PIC18LF43K22
- PIC18LF44K22
- PIC18LF45K22
- PIC18LF46K22

This family offers the advantages of all PIC18 microcontrollers – namely, high computational performance at an economical price – with the addition of high-endurance, Flash program memory. On top of these features, the PIC18(L)F2X/4XK22 family introduces design enhancements that make these microcontrollers a logical choice for many high-performance, power sensitive applications.

1.1 New Core Features

1.1.1 XLP TECHNOLOGY

All of the devices in the PIC18(L)F2X/4XK22 family incorporate a range of features that can significantly reduce power consumption during operation. Key items include:

- **Alternate Run Modes:** By clocking the controller from the Timer1 source or the internal oscillator block, power consumption during code execution can be reduced by as much as 90%.
- **Multiple Idle Modes:** The controller can also run with its CPU core disabled but the peripherals still active. In these states, power consumption can be reduced even further, to as little as 4% of normal operation requirements.
- **On-the-fly Mode Switching:** The power-managed modes are invoked by user code during operation, allowing the user to incorporate power-saving ideas into their application's software design.
- **Low Consumption in Key Modules:** The power requirements for both Timer1 and the Watchdog Timer are minimized. See **Section 27.0 "Electrical Specifications"** for values.

1.1.2 MULTIPLE OSCILLATOR OPTIONS AND FEATURES

All of the devices in the PIC18(L)F2X/4XK22 family offer ten different oscillator options, allowing users a wide range of choices in developing application hardware. These include:

- Four Crystal modes, using crystals or ceramic resonators
- Two External Clock modes, offering the option of using two pins (oscillator input and a divide-by-4 clock output) or one pin (oscillator input, with the second pin reassigned as general I/O)
- Two External RC Oscillator modes with the same pin options as the External Clock modes
- An internal oscillator block which contains a 16 MHz HFINTOSC oscillator and a 31 kHz LFINTOSC oscillator, which together provide eight user selectable clock frequencies, from 31 kHz to 16 MHz. This option frees the two oscillator pins for use as additional general purpose I/O.
- A Phase Lock Loop (PLL) frequency multiplier, available to both external and internal oscillator modes, which allows clock speeds of up to 64 MHz. Used with the internal oscillator, the PLL gives users a complete selection of clock speeds, from 31 kHz to 64 MHz – all without using an external crystal or clock circuit.

Besides its availability as a clock source, the internal oscillator block provides a stable reference source that gives the family additional features for robust operation:

- **Fail-Safe Clock Monitor:** This option constantly monitors the main clock source against a reference signal provided by the LFINTOSC. If a clock failure occurs, the controller is switched to the internal oscillator block, allowing for continued operation or a safe application shutdown.
- **Two-Speed Start-up:** This option allows the internal oscillator to serve as the clock source from Power-on Reset, or Wake-up from Sleep mode, until the primary clock source is available.

FIGURE 2-11: FSCM TIMING DIAGRAM

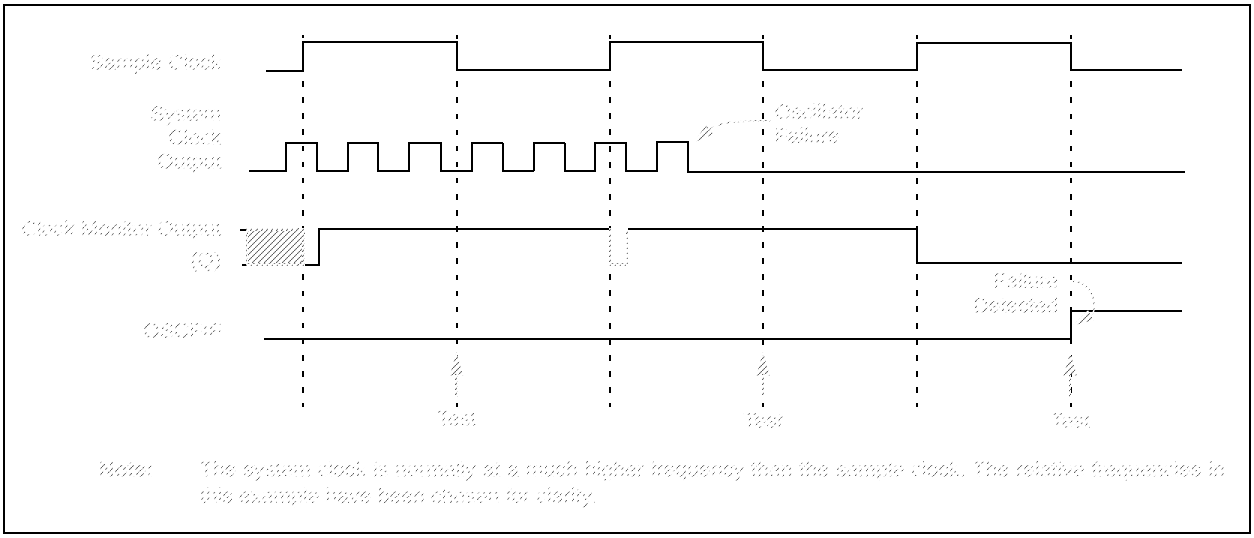


TABLE 2-4: REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR2	OSCFIP	C1IP	C2IP	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	122
OSCCON	IDLEN	IRCF<2:0>			OSTS	HFIOFS	SCS<1:0>		30
OSCCON2	PLLRDY	SOSCRUN	—	MFIOSEL	SOSCGO	PRISD	MFIOFS	LFIOFS	31
OSCTUNE	INTSRC	PLLEN	TUN<5:0>						35
PIE2	OSCFIE	C1IE	C2IE	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	118
PIR2	OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	113

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used by clock sources.

TABLE 2-5: CONFIGURATION REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CONFIG1H	IESO	FCMEN	PRICLKEN	PLLCFG	FOSC<3:0>				345
CONFIG2L	—	—	—	BORV<1:0>		BOREN<1:0>		$\overline{\text{PWRTEN}}$	346
CONFIG3H	MCLRE	—	P2BMX	T3CMX	HFOFST	CCP3MX	PBADEN	CCP2MX	348

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for clock sources.

4.3 Master Clear ($\overline{MCLR}$)

The $\overline{MCLR}$ pin provides a method for triggering an external Reset of the device. A Reset is generated by holding the pin low. These devices have a noise filter in the $\overline{MCLR}$ Reset path which detects and ignores small pulses. An internal weak pull-up is enabled when the pin is configured as the $\overline{MCLR}$ input.

The $\overline{MCLR}$ pin is not driven low by any internal Resets, including the WDT.

In PIC18(L)F2X/4XK22 devices, the $\overline{MCLR}$ input can be disabled with the MCLRE Configuration bit. When $\overline{MCLR}$ is disabled, the pin becomes a digital input. See **Section 10.6 "PORTE Registers"** for more information.

4.4 Power-on Reset (POR)

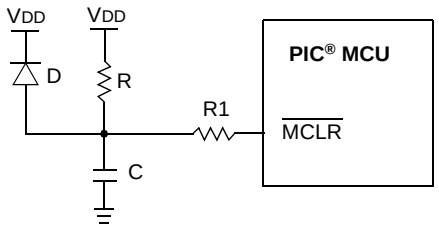
A Power-on Reset pulse is generated on-chip whenever VDD rises above a certain threshold. This allows the device to start in the initialized state when VDD is adequate for operation.

To take advantage of the POR circuitry either leave the pin floating, or tie the $\overline{MCLR}$ pin through a resistor to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. A minimum rise rate for VDD is specified. For a slow rise time, see Figure 4-2.

When the device starts normal operation (i.e., exits the Reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure proper operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

POR events are captured by the $\overline{POR}$ bit of the RCON register. The state of the bit is set to '0' whenever a POR occurs; it does not change for any other Reset event. $\overline{POR}$ is not reset to '1' by any hardware event. To capture multiple events, the user must manually set the bit to '1' by software following any POR.

FIGURE 4-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: 15 kΩ < R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 ≥ 1 kΩ will limit any current flowing into $\overline{MCLR}$ from external capacitor C, in the event of $\overline{MCLR}$/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

5.3 PIC18 Instruction Cycle

5.3.1 CLOCKING SCHEME

The microcontroller clock input, whether from an internal or external source, is internally divided by four to generate four non-overlapping quadrature clocks (Q1, Q2, Q3 and Q4). Internally, the program counter is incremented on every Q1; the instruction is fetched from the program memory and latched into the instruction register during Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 5-3.

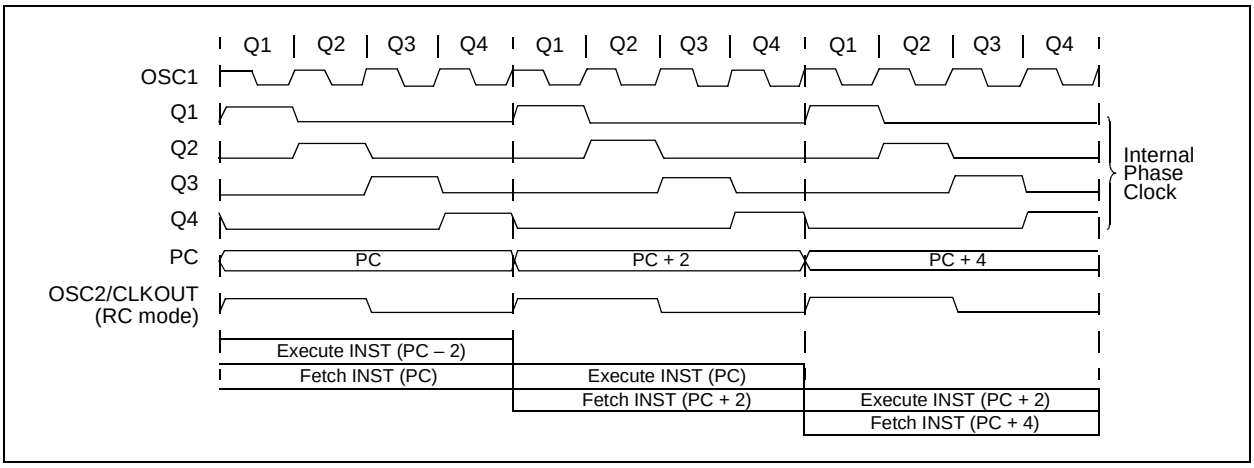
5.3.2 INSTRUCTION FLOW/PIPELINING

An “Instruction Cycle” consists of four Q cycles: Q1 through Q4. The instruction fetch and execute are pipelined in such a manner that a fetch takes one instruction cycle, while the decode and execute take another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 5-3).

A fetch cycle begins with the Program Counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 5-3: CLOCK/INSTRUCTION CYCLE



EXAMPLE 5-3: INSTRUCTION PIPELINE FLOW

	TCY0	TCY1	TCY2	TCY3	TCY4	TCY5
1. MOVLW 55h	Fetch 1	Execute 1				
2. MOVWF PORTB		Fetch 2	Execute 2			
3. BRA SUB_1			Fetch 3	Execute 3		
4. BSF PORTA, BIT3 (Forced NOP)				Fetch 4	Flush (NOP)	
5. Instruction @ address SUB_1					Fetch SUB_1	Execute SUB_1

Note: All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

TABLE 10-1: PORTA I/O SUMMARY

Pin Name	Function	TRIS Setting	ANSEL Setting	Pin Type	Buffer Type	Description
RA0/C12IN0-/AN0	RA0	0	0	O	DIG	LATA<0> data output; not affected by analog input.
		1	0	I	TTL	PORTA<0> data input; disabled when analog input enabled.
	C12IN0-	1	1	I	AN	Comparators C1 and C2 inverting input.
	AN0	1	1	I	AN	Analog input 0.
RA1/C12IN1-/AN1	RA1	0	0	O	DIG	LATA<1> data output; not affected by analog input.
		1	0	I	TTL	PORTA<1> data input; disabled when analog input enabled.
	C12IN1-	1	1	I	AN	Comparators C1 and C2 inverting input.
	AN1	1	1	I	AN	Analog input 1.
RA2/C2IN+/AN2/ DACOUT/VREF-	RA2	0	0	O	DIG	LATA<2> data output; not affected by analog input; disabled when DACOUT enabled.
		1	0	I	TTL	PORTA<2> data input; disabled when analog input enabled; disabled when DACOUT enabled.
	C2IN+	1	1	I	AN	Comparator C2 non-inverting input.
	AN2	1	1	I	AN	Analog output 2.
	DACOUT	x	1	O	AN	DAC Reference output.
	VREF-	1	1	I	AN	A/D reference voltage (low) input.
RA3/C1IN+/AN3/ VREF+	RA3	0		O	DIG	LATA<3> data output; not affected by analog input.
		1	0	I	TTL	PORTA<3> data input; disabled when analog input enabled.
	C1IN+	1	1	I	AN	Comparator C1 non-inverting input.
	AN3	1	1	I	AN	Analog input 3.
	VREF+	1	1	I	AN	A/D reference voltage (high) input.
RA4/CCP5/C1OUT/ SRQ/T0CKI	RA4	0	—	O	DIG	LATA<4> data output.
		1	—	I	ST	PORTA<4> data input; default configuration on POR.
	CCP5	0	—	O	DIG	CCP5 Compare output/PWM output, takes priority over RA4 output.
		1	—	I	ST	Capture 5 input/Compare 5 output/ PWM 5 output.
	C1OUT	0	—	O	DIG	Comparator C1 output.
	SRQ	0	—	O	DIG	SR latch Q output; take priority over CCP 5 output.
	T0CKI	1	—	I	ST	Timer0 external clock input.
RA5/C2OUT/SRNQ/ SS1/ HLVDIN/AN4	RA5	0	0	O	DIG	LATA<5> data output; not affected by analog input.
		1	0	I	TTL	PORTA<5> data input; disabled when analog input enabled.
	C2OUT	0	0	O	DIG	Comparator C2 output.
	SRNQ	0	0	O	DIG	SR latch $\overline{Q}$ output.
	$\overline{SS1}$	1	0	I	TTL	SPI slave select input (MSSP1).
	HLVDIN	1	1	I	AN	High/Low-Voltage Detect input.
	AN4	1	1	I	AN	A/D input 4.
RA6/CLKO/OSC2	RA6	0	—	O	DIG	LATA<6> data output; enabled in INTOSC modes when CLKO is not enabled.
		1	—	I	TTL	PORTA<6> data input; enabled in INTOSC modes when CLKO is not enabled.
	CLKO	x	—	O	DIG	In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
	OSC2	x	—	O	XTAL	Oscillator crystal output; connects to crystal or resonator in Crystal Oscillator mode.
RA7/CLKI/OSC1	RA7	0	—	O	DIG	LATA<7> data output; disabled in external oscillator modes.
		1	—	I	TTL	PORTA<7> data input; disabled in external oscillator modes.
	CLKI	x	—	I	AN	External clock source input; always associated with pin function OSC1.
	OSC1	x	—	I	XTAL	Oscillator crystal input or external clock source input ST buffer when configured in RC mode; CMOS otherwise.

Legend: AN = Analog input or output; TTL = TTL compatible input; HV = High Voltage; OD = Open Drain; XTAL = Crystal; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C.

TABLE 10-15: REGISTERS ASSOCIATED WITH PORTE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
ANSELE(1)	—	—	—	—	—	ANSE2	ANSE1	ANSE0	151
INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	110
LATE(1)	—	—	—	—	—	LATE2	LATE1	LATE0	152
PORTE	—	—	—	—	RE3	RE2(1)	RE1(1)	RE0(1)	149
SLRCON	—	—	—	SLRE(1)	SLRD(1)	SLRC	SLRB	SLRA	153
TRISE	WPUE3	—	—	—	—	TRISE2(1)	TRISE1(1)	TRISE0(1)	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for PORTE.

Note 1: Available on PIC18(L)F4XK22 devices.

TABLE 10-16: CONFIGURATION REGISTERS ASSOCIATED WITH PORTE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
CONFIG3H	MCLRE	—	P2BMX	T3CMX	HFOFST	CCP3MX	PBADEN	CCP2MX	348
CONFIG4L	$\overline{\text{DEBUG}}$	XINST	—	—	—	LVP(1)	—	STRVEN	349

Legend: — = unimplemented locations, read as '0'. Shaded bits are not used for Interrupts.

Note 1: Can only be changed when in high voltage programming mode.

REGISTER 14-2: CCPxCON: ENHANCED CCPx CONTROL REGISTER

R/x-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PxM<1:0>		DCxB<1:0>		CCPxM<3:0>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Reset
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **PxM<1:0>**: Enhanced PWM Output Configuration bits

If CCPxM<3:2> = 00, 01, 10: (Capture/Compare modes)

xx = PxA assigned as Capture/Compare input; PxB, PxC, PxD assigned as port pins

Half-Bridge ECCP Modules(1):

If CCPxM<3:2> = 11: (PWM modes)

0x = Single output; PxA modulated; PxB assigned as port pin

1x = Half-Bridge output; PxA, PxB modulated with dead-band control

Full-Bridge ECCP Modules(1):

If CCPxM<3:2> = 11: (PWM modes)

00 = Single output; PxA modulated; PxB, PxC, PxD assigned as port pins

01 = Full-Bridge output forward; PxD modulated; PxA active; PxB, PxC inactive

10 = Half-Bridge output; PxA, PxB modulated with dead-band control; PxC, PxD assigned as port pins

11 = Full-Bridge output reverse; PxB modulated; PxC active; PxA, PxD inactive

bit 5-4 **DCxB<1:0>:** PWM Duty Cycle Least Significant bits

Capture mode:

Unused

Compare mode:

Unused

PWM mode:

These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

Note 1: See Table 14-1 to determine full-bridge and half-bridge ECCPs for the device being used.

REGISTER 14-6: PWMxCON: ENHANCED PWM CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PxRSEN	PxDC<6:0>						
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **PxRSEN:** PWM Restart Enable bit
- 1 = Upon auto-shutdown, the CCPxASE bit clears automatically once the shutdown event goes away; the PWM restarts automatically
- 0 = Upon auto-shutdown, CCPxASE must be cleared in software to restart the PWM

bit 6-0 **PxDC<6:0>:** PWM Delay Count bits

PxDCx = Number of FOSC/4 (4 * TOSC) cycles between the scheduled time when a PWM signal **should** transition active and the **actual** time it transitions active

REGISTER 14-7: PSTRxCON: PWM STEERING CONTROL REGISTER(1)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
—	—	—	STRxSYNC	STRxD	STRxC	STRxB	STRxA
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **STRxSYNC:** Steering Sync bit
- 1 = Output steering update occurs on next PWM period
- 0 = Output steering update occurs at the beginning of the instruction cycle boundary

bit 3 **STRxD:** Steering Enable bit D
- 1 = PxD pin has the PWM waveform with polarity control from CCPxM<1:0>
- 0 = PxD pin is assigned to port pin

bit 2 **STRxC:** Steering Enable bit C
- 1 = PxC pin has the PWM waveform with polarity control from CCPxM<1:0>
- 0 = PxC pin is assigned to port pin

bit 1 **STRxB:** Steering Enable bit B
- 1 = PxB pin has the PWM waveform with polarity control from CCPxM<1:0>
- 0 = PxB pin is assigned to port pin

bit 0 **STRxA:** Steering Enable bit A
- 1 = PxA pin has the PWM waveform with polarity control from CCPxM<1:0>
- 0 = PxA pin is assigned to port pin

Note 1: The PWM Steering mode is available only when the CCPxCON register bits CCPxM<3:2> = 11 and PxM<1:0> = 00.

15.6.13 MULTI -MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-Master mode support is achieved by bus arbitration. When the master outputs address/data bits onto the SDAx pin, arbitration takes place when the master outputs a '1' on SDAx, by letting SDAx float high and another master asserts a '0'. When the SCLx pin floats high, data should be stable. If the expected data on SDAx is a '1' and the data sampled on the SDAx pin is '0', then a bus collision has taken place. The master will set the Bus Collision Interrupt Flag, BCLxIF, and reset the I^2C port to its Idle state (Figure 15-32).

If a transmit was in progress when the bus collision occurred, the transmission is halted, the BF flag is cleared, the SDAx and SCLx lines are deasserted and the SSPxBUF can be written to. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

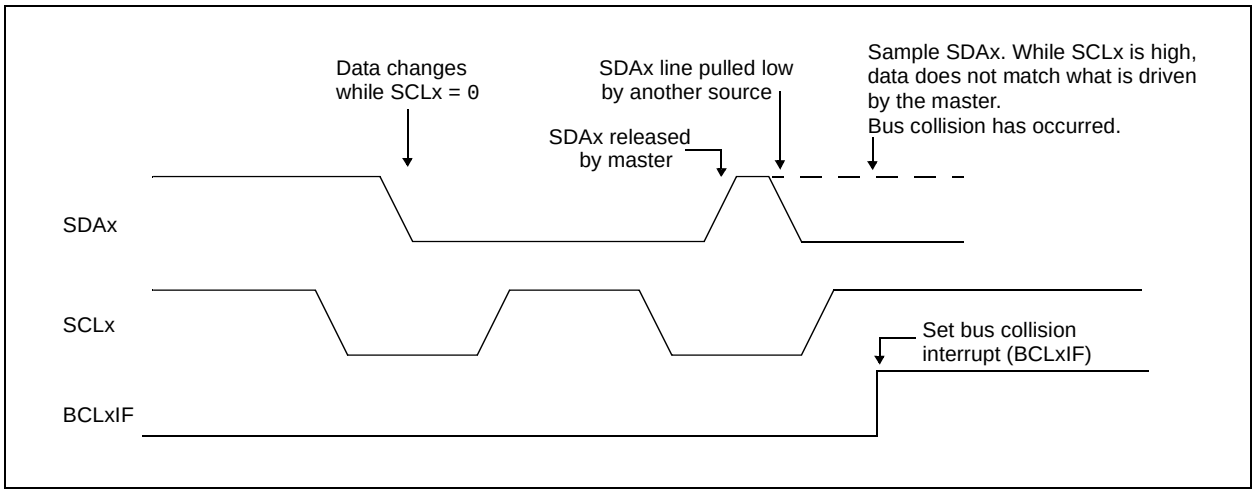
If a Start, Repeated Start, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDAx and SCLx lines are deasserted and the respective control bits in the SSPxCON2 register are cleared. When the user services the bus collision Interrupt Service Routine and if the I^2C bus is free, the user can resume communication by asserting a Start condition.

The master will continue to monitor the SDAx and SCLx pins. If a Stop condition occurs, the SSPxIF bit will be set.

A write to the SSPxBUF will start the transmission of data at the first data bit, regardless of where the transmitter left off when the bus collision occurred.

In Multi-Master mode, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I^2C bus can be taken when the P bit is set in the SSPxSTAT register, or the bus is Idle and the S and P bits are cleared.

FIGURE 15-32: BUS COLLISION TIMING FOR TRANSMIT AND ACKNOWLEDGE



REGISTER 16-2: RCSTAx: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit

1 = Serial port enabled (configures RXx/DTx and TXx/CKx pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-bit Receive Enable bit

1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit

Asynchronous mode:

Don't care

Synchronous mode – Master:

1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.

Synchronous mode – Slave

Don't care

bit 4 **CREN:** Continuous Receive Enable bit

Asynchronous mode:

1 = Enables receiver
0 = Disables receiver

Synchronous mode:

1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit

Asynchronous mode 9-bit (RX9 = 1):

1 = Enables address detection, enable interrupt and load the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit

Asynchronous mode 8-bit (RX9 = 0):

Don't care

bit 2 **FERR:** Framing Error bit

1 = Framing error (can be updated by reading RCREGx register and receive next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit

1 = Overrun error (can be cleared by clearing bit CREN)
0 = No overrun error

bit 0 **RX9D:** Ninth bit of Received Data

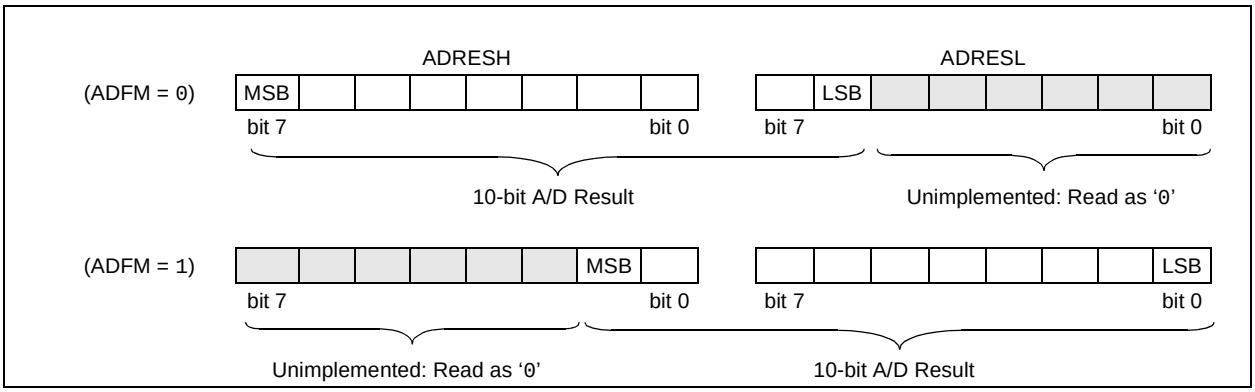
This can be address/data bit or a parity bit and must be calculated by user firmware.

17.1.7 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON2 register controls the output format.

Figure 17-2 shows the two output formats.

FIGURE 17-2: 10-BIT A/D CONVERSION RESULT FORMAT



REGISTER 18-2: CM2CON1: COMPARATOR 1 AND 2 CONTROL REGISTER

R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
MC1OUT	MC2OUT	C1RSEL	C2RSEL	C1HYS	C2HYS	C1SYNC	C2SYNC
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **MC1OUT:** Mirror Copy of C1OUT bit

bit 6 **MC2OUT:** Mirror Copy of C2OUT bit

bit 5 **C1RSEL:** Comparator C1 Reference Select bit
1 = FVR BUF1 routed to C1VREF input
0 = DAC routed to C1VREF input

bit 4 **C2RSEL:** Comparator C2 Reference Select bit
1 = FVR BUF1 routed to C2VREF input
0 = DAC routed to C2VREF input

bit 3 **C1HYS:** Comparator C1 Hysteresis Enable bit
1 = Comparator C1 hysteresis enabled
0 = Comparator C1 hysteresis disabled

bit 2 **C2HYS:** Comparator C2 Hysteresis Enable bit
1 = Comparator C2 hysteresis enabled
0 = Comparator C2 hysteresis disabled

bit 1 **C1SYNC:** C1 Output Synchronous Mode bit
1 = C1 output is synchronized to rising edge of TMR1 clock (T1CLK)
0 = C1 output is asynchronous

bit 0 **C2SYNC:** C2 Output Synchronous Mode bit
1 = C2 output is synchronized to rising edge of TMR1 clock (T1CLK)
0 = C2 output is asynchronous

19.3.2 CAPACITANCE CALIBRATION

There is a small amount of capacitance from the internal A/D Converter sample capacitor as well as stray capacitance from the circuit board traces and pads that affect the precision of capacitance measurements. A measurement of the stray capacitance can be taken by making sure the desired capacitance to be measured has been removed. The measurement is then performed using the following steps:

1. Initialize the A/D Converter and the CTMU.
2. Set EDG1STAT (= 1).
3. Wait for a fixed delay of time *t*.
4. Clear EDG1STAT.
5. Perform an A/D conversion.
6. Calculate the stray and A/D sample capacitances:

$$C_{OFFSET} = C_{STRAY} + C_{AD} = (I \cdot t)/V$$

where *I* is known from the current source measurement step, *t* is a fixed delay and *V* is measured by performing an A/D conversion.

This measured value is then stored and used for calculations of time measurement or subtracted for capacitance measurement. For calibration, it is expected that the capacitance of $C_{STRAY} + C_{AD}$ is approximately known. C_{AD} is approximately 4 pF.

An iterative process may need to be used to adjust the time, *t*, that the circuit is charged to obtain a reasonable voltage reading from the A/D Converter. The value of *t* may be determined by setting C_{OFFSET} to a theoretical value, then solving for *t*. For example, if C_{STRAY} is theoretically calculated to be 11 pF, and *V* is expected to be 70% of V_{DD}, or 2.31V, then *t* would be:

$$(4\ pF + 11\ pF) \bullet 2.31V/0.55\ \mu A$$

or 63 μs.

See Example 19-3 for a typical routine for CTMU capacitance calibration.

23.7 Operation During Sleep

When enabled, the HLVD circuitry continues to operate during Sleep. If the device voltage crosses the trip point, the HLVDIF bit will be set and the device will wake-up from Sleep. Device execution will continue from the interrupt vector address if interrupts have been globally enabled.

23.8 Effects of a Reset

A device Reset forces all registers to their Reset state. This forces the HLVD module to be turned off.

TABLE 23-1: REGISTERS ASSOCIATED WITH HIGH/LOW-VOLTAGE DETECT MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
HLVDCON	VDIRMAG	BGVST	IRVST	HLVDEN	HLVDL<3:0>				337
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	109
IPR2	OSCFIP	C1IP	C2IP	EEIP	BCL1IP	HLVDIP	TMR3IP	CCP2IP	122
PIE2	OSCFIE	C1IE	C2IE	EEIE	BCL1IE	HLVDIE	TMR3IE	CCP2IE	118
PIR2	OSCFIF	C1IF	C2IF	EEIF	BCL1IF	HLVDIF	TMR3IF	CCP2IF	113
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	151

Legend: — = unimplemented locations, read as '0'. Shaded bits are unused by the HLVD module.

DAW **Decimal Adjust W Register**

Syntax: DAW

Operands: None

Operation: If [W<3:0> > 9] or [DC = 1] then
(W<3:0>) + 6 → W<3:0>;
else
(W<3:0>) → W<3:0>;

If [W<7:4> + DC > 9] or [C = 1] then
(W<7:4>) + 6 + DC → W<7:4> ;
else
(W<7:4>) + DC → W<7:4>

Status Affected: C

Encoding:

0000	0000	0000	0111

Description: DAW adjusts the 8-bit value in W, resulting from the earlier addition of two variables (each in packed BCD format) and produces a correct packed BCD result.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register W	Process Data	Write W

Example1:

```
DAW
```

Before Instruction
W = A5h
C = 0
DC = 0
After Instruction
W = 05h
C = 1
DC = 0

Example 2:

Before Instruction
W = CEh
C = 0
DC = 0
After Instruction
W = 34h
C = 1
DC = 0

DECF **Decrement f**

Syntax: DECF f {,d {,a}}

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

Operation: (f) – 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0000	01da	ffff	ffff

Description: Decrement register ‘f’. If ‘d’ is ‘0’, the result is stored in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’ (default).
If ‘a’ is ‘0’, the Access Bank is selected. If ‘a’ is ‘1’, the BSR is used to select the GPR bank.
If ‘a’ is ‘0’ and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 “Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode”** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register ‘f’	Process Data	Write to destination

Example: DECF CNT, 1, 0

Before Instruction
CNT = 01h
Z = 0
After Instruction
CNT = 00h
Z = 1

CALLW **Subroutine Call Using WREG**

Syntax: CALLW

Operands: None

Operation: (PC + 2) → TOS,
(W) → PCL,
(PCLATH) → PCH,
(PCLATU) → PCU

Status Affected: None

Encoding:

0000	0000	0001	0100

Description: First, the return address (PC + 2) is pushed onto the return stack. Next, the contents of W are written to PCL; the existing value is discarded. Then, the contents of PCLATH and PCLATU are latched into PCH and PCU, respectively. The second cycle is executed as a NOP instruction while the new next instruction is fetched. Unlike CALL, there is no option to update W, Status or BSR.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read WREG	PUSH PC to stack	No operation
No operation	No operation	No operation	No operation

Example: HERE CALLW

Before Instruction
PC = address (HERE)
PCLATH = 10h
PCLATU = 00h
W = 06h
After Instruction
PC = 001006h
TOS = address (HERE + 2)
PCLATH = 10h
PCLATU = 00h
W = 06h

MOVSF **Move Indexed to f**

Syntax: MOVSF [z_s], f_d

Operands: $0 \le z_s \le 127$
$0 \le f_d \le 4095$

Operation: ((FSR2) + z_s) → f_d

Status Affected: None

Encoding:

1st word (source)	1110	1011	0zzz	$zzzz_s$
2nd word (destin.)	1111	ffff	ffff	$ffff_d$

Description: The contents of the source register are moved to destination register 'f_d'. The actual address of the source register is determined by adding the 7-bit literal offset 'z_s' in the first word to the value of FSR2. The address of the destination register is specified by the 12-bit literal 'f_d' in the second word. Both addresses can be anywhere in the 4096-byte data space (000h to FFFh).
The MOVSF instruction cannot use the PCL, TOSU, TOSH or TOSL as the destination register.
If the resultant source address points to an indirect addressing register, the value returned will be 00h.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Determine source addr	Determine source addr	Read source reg
Decode	No operation No dummy read	No operation	Write register 'f' (dest)

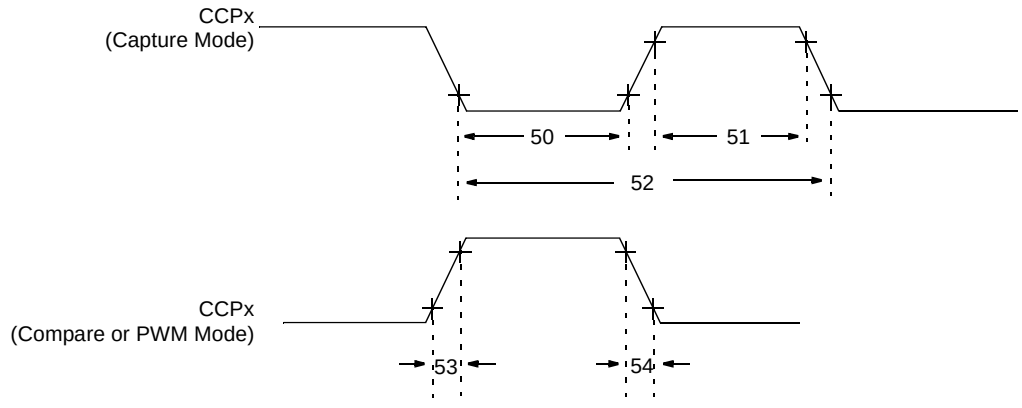
Example: MOVSF [05h], REG2

Before Instruction
FSR2 = 80h
Contents of 85h = 33h
REG2 = 11h
After Instruction
FSR2 = 80h
Contents of 85h = 33h
REG2 = 33h

TABLE 27-12: TIMER0 AND TIMER1/3/5 EXTERNAL CLOCK REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
42	Tt0P	T0CKI Period	No prescaler	TCY + 10	—	ns	
			With prescaler	Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4,..., 256)
45	Tt1H	TxCKI High Time	Synchronous, no prescaler	0.5 TCY + 20	—	ns	
			Synchronous, with prescaler	10	—	ns	
			Asynchronous	30	—	ns	
46	Tt1L	TxCKI Low Time	Synchronous, no prescaler	0.5 TCY + 5	—	ns	
			Synchronous, with prescaler	10	—	ns	
			Asynchronous	30	—	ns	
47	Tt1P	TxCKI Input Period	Synchronous	Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	ns	
	Ft1	TxCKI Clock Input Frequency Range		DC	50	kHz	
48	Tcke2tmrI	Delay from External TxCKI Clock Edge to Timer Increment		2 TOSC	7 TOSC	—	

FIGURE 27-12: CAPTURE/COMPARE/PWM TIMINGS (ALL CCP MODULES)



Note: Refer to Figure 27-6 for load conditions.

FIGURE 27-15: EXAMPLE SPI SLAVE MODE TIMING (CKE = 0)

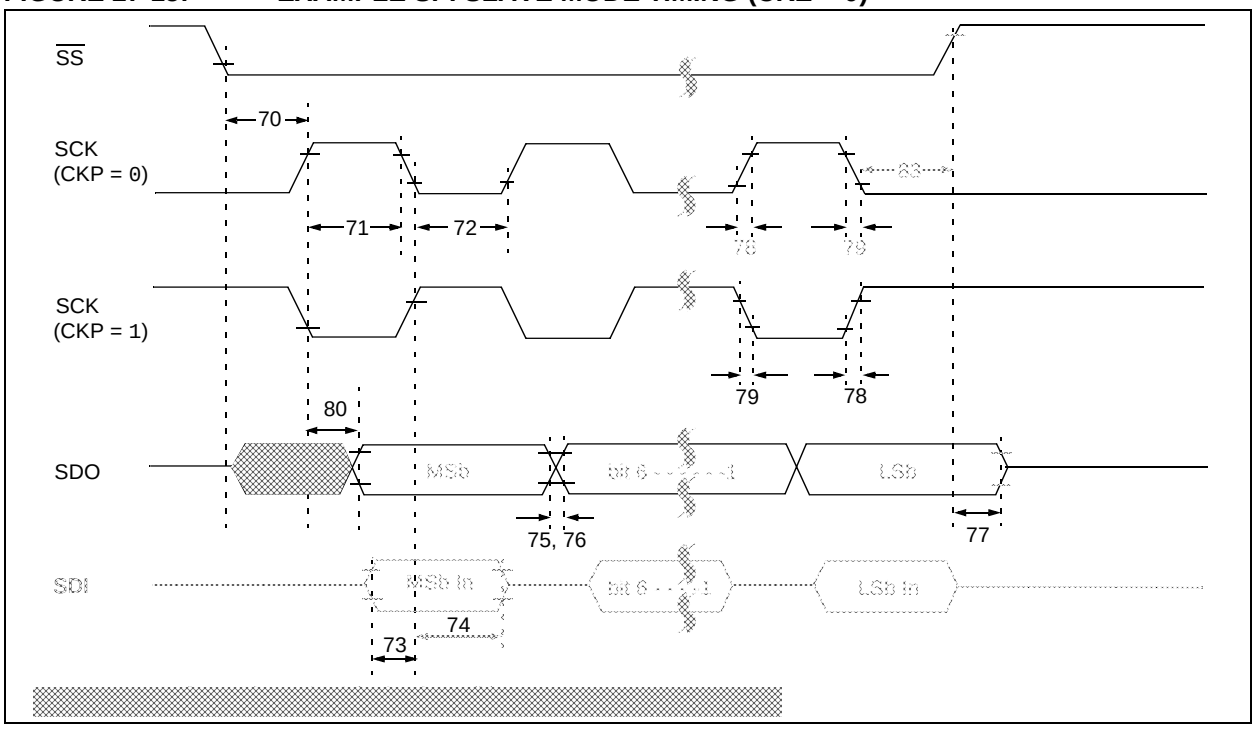
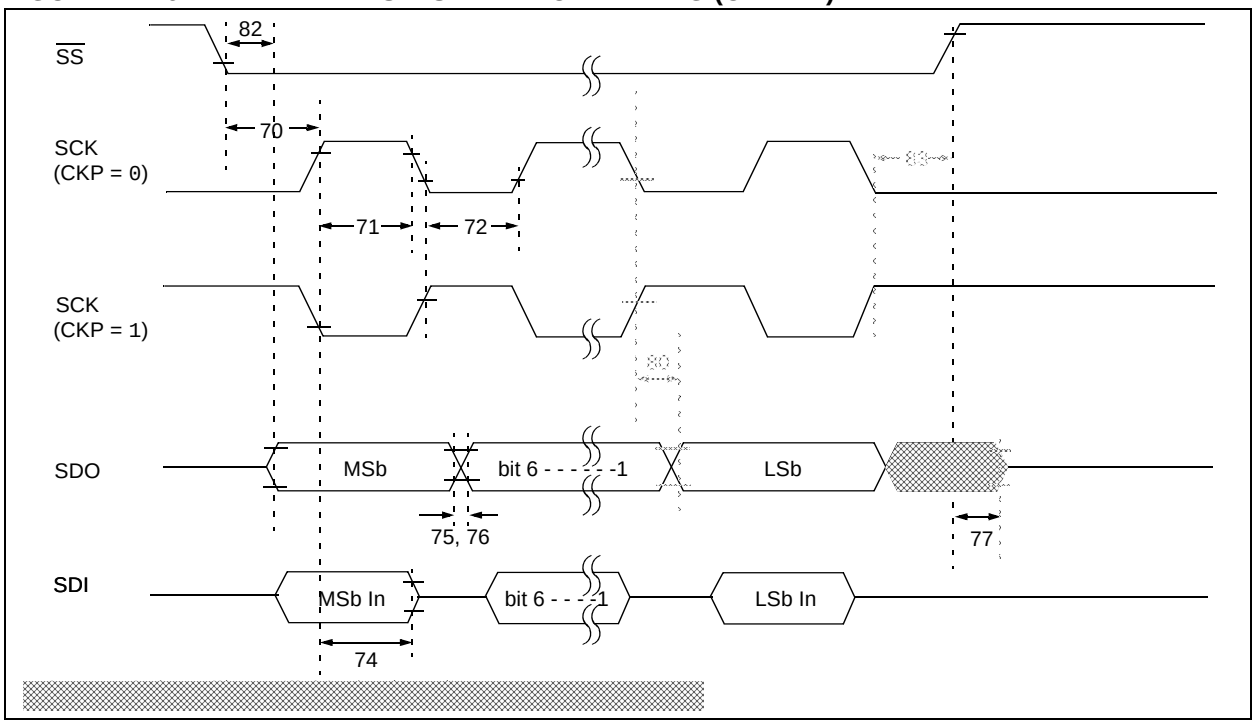
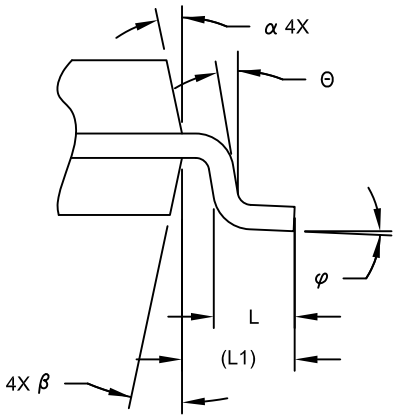


FIGURE 27-16: EXAMPLE SPI SLAVE MODE TIMING (CKE = 1)

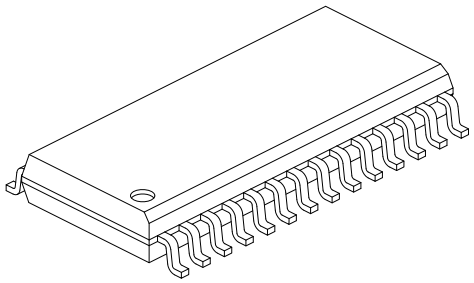


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

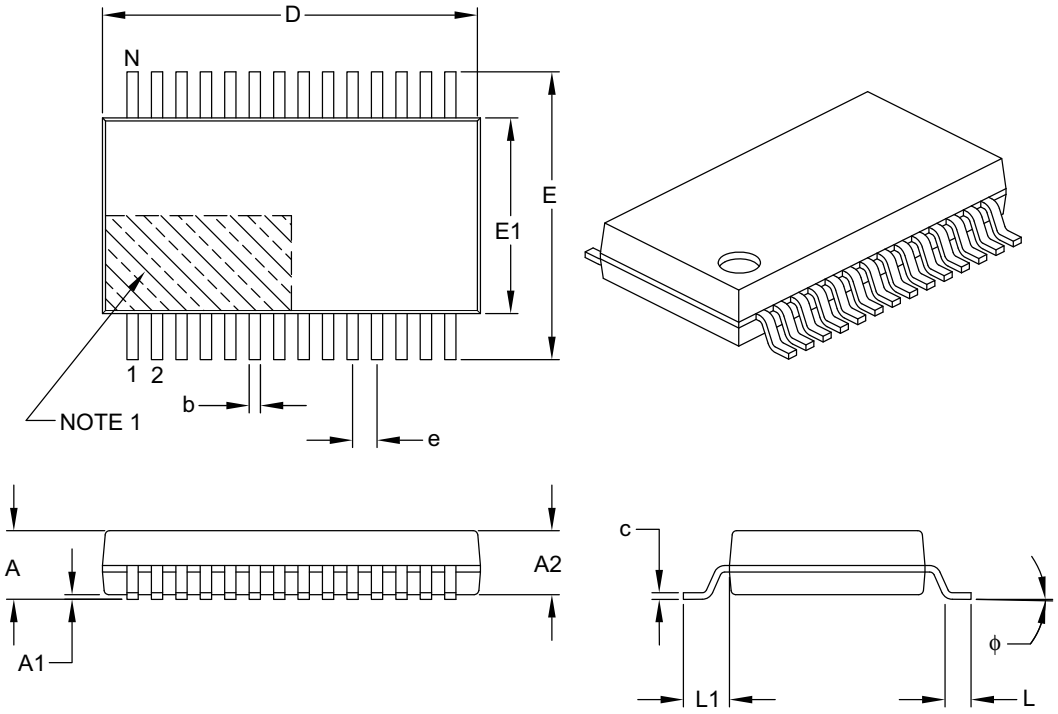
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B